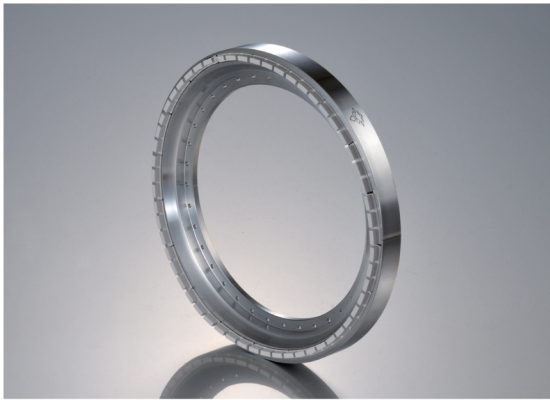


For LT/LN Wafers / Nanomate Masspower

Low-Damage Grinding of LT/LN Wafers

Because fragile LT wafers used as the SAW filter tend to get broken in processing, improving the processed surface roughness is required. "Nanomate Masspower", having a high porosity abrasive layer with excellent durability of sharpness, provides low-damage processing enabled by the added body shape with a function of efficiently feeding to the grinding point.

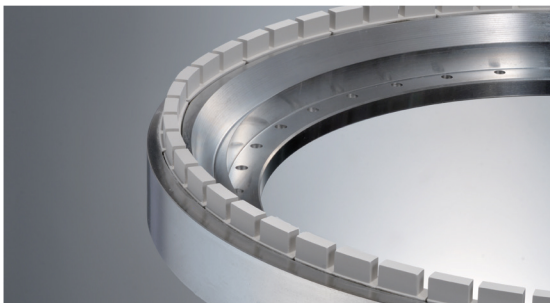


■ Features

- High porosity abrasive layer for long sharpness retention.
- Newly developed body shape to uniformly supply grinding fluid to grinding points.
- Highly efficient and high quality grinding.

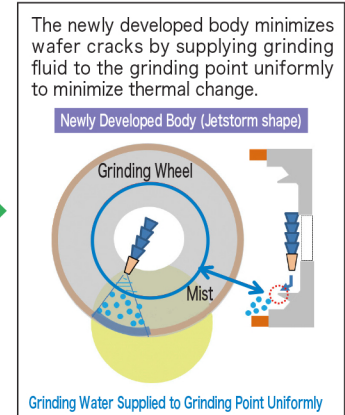
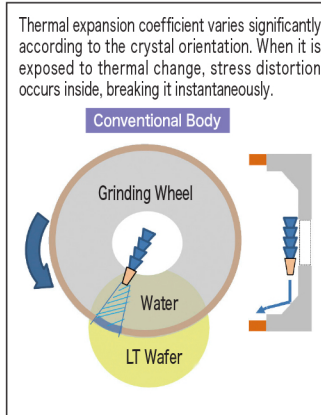
■ Applications

- Precision surface grinding of LT/LN wafers



Newly Developed Body (Jetstorm Shape)

■ LT Wafer Grinding Problem Solving



For GaN / Sapphire Wafers / Nanomate Premium

Reduces Grinding Time

The adjustment of the binding grade and bond has enabled grinding of difficult-to-grind materials with fine grains that have been difficult to grind with conventional wheels. This wheel ensures high-speed and mirror finishing of GaN wafers.



■ Features

- Grinding of difficult-to-machine materials.
- High-speed and near mirror finishing.

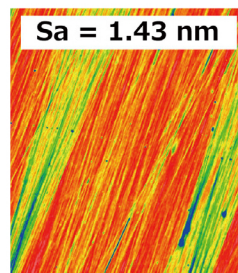
■ Applications

- Precision surface grinding of GaN / Sapphire wafers

■ Results from Grinding Single-Crystal GaN Wafers

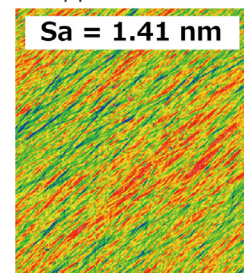
GaN Wafer (Ga Surface)	2 Inch			4 Inch		
	Grinding Process			Grinding Process		
	Rough	Finish	Rough	Finish		
Grit Size (Grain Dia.)	#2000(9 μm)	#6000(1.5 μm)	#2000(9 μm)	#6000(1.5 μm)		
Stock Removal (μm)	50-100		10	50-100		10
Feed Rate (μm/min)	30	60	90	20	30	60
				90	20	
Wear Rate (%)	7	15	27	100	12	20
					35	100
Surface Quality Ra (nm)	90	-	-	1-2	100	-
						2

■ GaN Wafer



Grain Size 1.5 μm

■ Sapphire Wafer



Grain Size 0.5 μm

Measured by : zygo nexview FOV : 450 μm